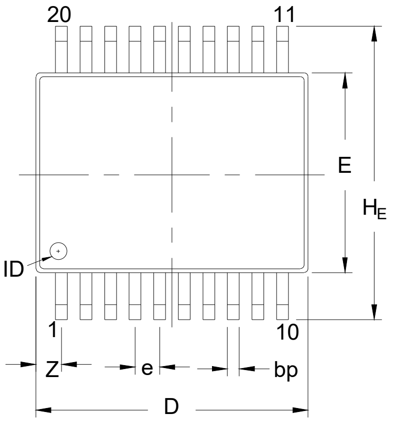
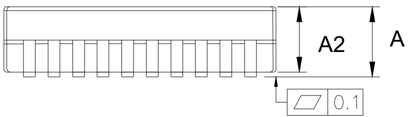
Package Outline Drawing

Package Code: PYG20
20-SSOP 5.3 mm Body, 0.65mm Pitch
PSC-4032-03, Revision: 01, Date Created: Aug 9, 2024

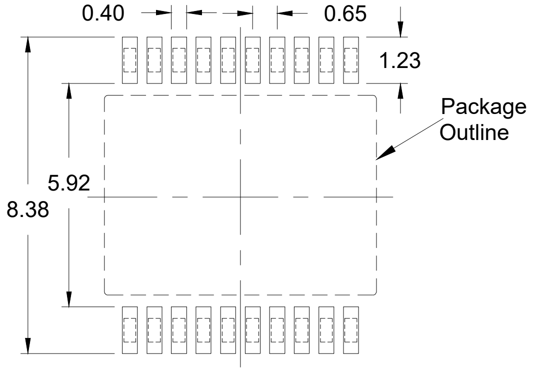
BASED ON JEDEC JEP95: MO-150



TOP VIEW



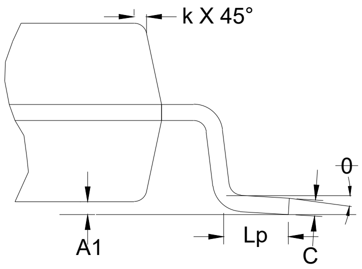
SIDE VIEW



RECOMMENDED LAND PATTERN
(PCB Top View, SMD Design)

1. Dimensions
2. Weight ≤ 0.3 g
3. Body Material LOW STRESS EPOXY
4. Lead Material FeNi-ALLOY or Cu-ALLOY
5. Lead Finish SOLDER PLATING
6. Lead Form Z-BENDS

VIEW X



DIMENSIONS OF SUB-GROUP C1	
A min	1.73
A1 min	0.05
A1 max	0.21
A2 min	1.68
A2 max	1.78
c min	0.09
c max	0.20
D min*	7.07
D max*	7.33
E min*	5.20
E max*	5.38
k min	0.25
θ max	0°
θ max	10°

* WITHOUT MOLD FLASH

DIMENSIONS OF SUB-GROUP B1	
A max	1.99
bp min	0.25
bp max	0.38
e nom	0.65
H_E min	7.40
H_E max	8.20
Lpmin	0.63
Z max	0.74

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.